

VIGON® US

Water-based cleaning medium for flux removal



VIGON® US is a water-based medium specifically developed for the use in ultrasonic, spray-under-immersion and centrifugal cleaning equipment. Based on MPC® Technology, VIGON® US removes all types of flux residues from electronic assemblies, ceramic hybrids and lead frames.

Areas of application: PCB's, ceramic hybrids, power modules, lead frames		Additional product information:
Low solid flux residues*	++	Technical Information 2: Overview of all fluxes and solder pastes tested Technical Information 3: Overview regarding material compatibility Application Recommendation: Specific process parameters for your cleaning trial MPC® Technology Information Sheet: Additional information on MPC® Technology
Rosin-based flux residues*	++	
Water soluble flux residues*	++	
Solder pastes (unsoldered)	++	
SMT-adhesives or conductive adhesives	-	
Misprinted thick film pastes	+	

++ highly recommended, best results + recommended 0 possible - not recommended
 * Valid for all standard, lead-free and lead-based solders

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Advantages compared to other cleaners:

- Due to its wide process window VIGON® US easily removes flux residues and solder pastes.
- VIGON® US has no flash point and does not require explosion proof equipment.
- The cleaning medium was specifically designed for the use in dip tank systems.
- Due to its formulation, VIGON® US can be easily rinsed without leaving residues on the surface and provides low ionic contamination of cleaned parts.
- Its high bath loading capacity ensures an extended bath life, low maintenance and reduced cleaning agent costs.
- VIGON® US works exceptionally well for the cleaning in capillary spaces and is also suitable for cleaning under low standoff components.
- Low odor.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.





VIGON® US is approved by leading international cleaning equipment manufacturers. Written approvals can be obtained from ZESTRON.



Process Steps	1. Cleaning	2. Rinsing	3. Drying
Ultrasonic	VIGON® US	DI-water	Hot or circulated air
Spray-under-immersion	VIGON® US	DI-water	Hot or circulated air
Centrifugal cleaning	VIGON® US	DI-water	Hot air

Technical Data		
Please note that the information below represents VIGON® US at 20 % concentration.		
Density	(g/ccm) at 20°C/68°F	0.99
Surface tension	(mN/m) at 25°C/77°F	30.8
Boiling range	°C/°F	165 – 212 / 329 – 414
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	11
Vapor pressure	(mbar) bei 20°C/68°F	19
Cleaning temperature	°C/°F	40 – 60 / 104 – 140
Solubility in water		Soluble
Application concentration ¹	Concentrate in %	15 – 30
HMIS Rating	Health-Flammability-Reactivity	0 – 0 – 0

¹ VIGON® US is recommended to be diluted with DI-water only.

PRODUCT FEATURES	
 <p>Extensively tested and suitable for cleaning of lead-free solder pastes</p>	 <p>MPC® Technology ensures an extremely long bath life when used in a closed loop system</p>
 <p>100% compliance with EU guidelines (RoHS 1 & 2, WEEE)</p>	 <p>Product is free of any critical substances according to SIN & SVHC lists</p>

Filter recommendation:

- To take full advantage of the MPC® technology and further extend the bath life of VIGON® US, filtration is recommended.
- For details, please request our “Filter Recommendation” sheet.

Environmental and health and safety regulations:

- VIGON® US is formulated free of any halogenated compounds and is environmentally friendly.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- VIGON® US is available as concentrate solution in 1l bottles, 5l or 25l containers and 200l drums.
- Store VIGON® US in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For application in spray-in-air systems such as inline and batch equipment, we recommend the MPC® based cleaner VIGON®A 201.

Cleaning standards:

Electronic assemblies cleaned with VIGON® US in a ZESTRON specified process meet the following industry standards:

- IPC-A-610 Visual cleanliness
- J-STD 001 Ionic and resin cleanliness
- IPC-TM 650 and DIN 32513 (surface resistance)
- J-STD 003 Solderability